

FEATURES

- Low on-resistance and high-current density due to thick Al wirebonding
- Full turnkey available from wafer saw through test and packing
- Green materials: Pb-free plating and halogen-free mold compound

UNDER DEVELOPMENT

Environmentally friendly die attach Pb-free solder

PROCESS HIGHLIGHTS

- Interconnect: Thick Al wirebonding technology
- Plating: 100% Matte Sn
- Marking: Laser mark
- 100% Auto appearance check for automotive grade

D2PAK (TO-263)

D2PAK follows the JEDEC standard (TO-263) for high-power discrete products.

Applications

D2PAK is suitable for high-power applications (over 100A available), designed for low on-resistance and high-speed switching MOSFETs.

- Motor drivers
- Power supply circuits
- DC-DC converters
- Key applications for automotive in body, safety and lighting

Reliability Qualification

Amkor packages are assembled with proven reliable semiconductor materials. All reliability testing includes:

- JEDEC standard pre-conditioning except for high temperature storage
- 85°C/85% RH, 168 hours, IR reflow 260°C 3X
- H3TRB: 85°C/85% RH, 1000 hours
- uHAST: 130°C/85% RH, 96 hours
- ► Temp cycle: -55°C to 150°C, 1000 cycles
- High temp storage: 150°C, 1000 hours

Test Services

Amkor offers full turnkey business for all power discrete products with the capability to test various types of power devices including MOSFETs, intelligent power devices, etc.

- Power discrete test capability
 - DC

 - Avalanche test
 - > Thermal resistance
- Program conversion
- Electrical failure analysis
- Integrated test, marking, vision inspection and tape & reel services



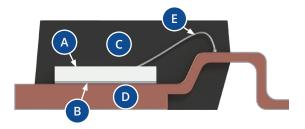
^{*1} Sampling test only

D2PAK (TO-263)

Standard Materials

- Leadframe: Bare copper
- Die attach: Pb solder
- Interconnect: Al wire
- Mold compound: Halogen-free

Cross Section



Leadframe

Al wire

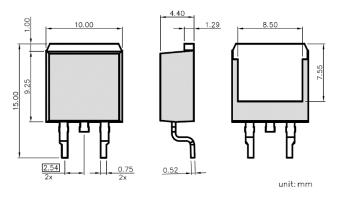
- Die attach material
- Mold compound

Shipping

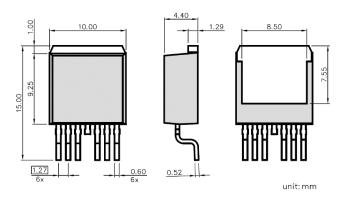
- Tape and reel packing
 - ▶ 800 pcs per reel
 - ▶ Tape width: 24 mm
 - > Reel Φ = 330 mm
- Barcode packing label

Package Outline Drawing

D2PAK



D2PAK7L



















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